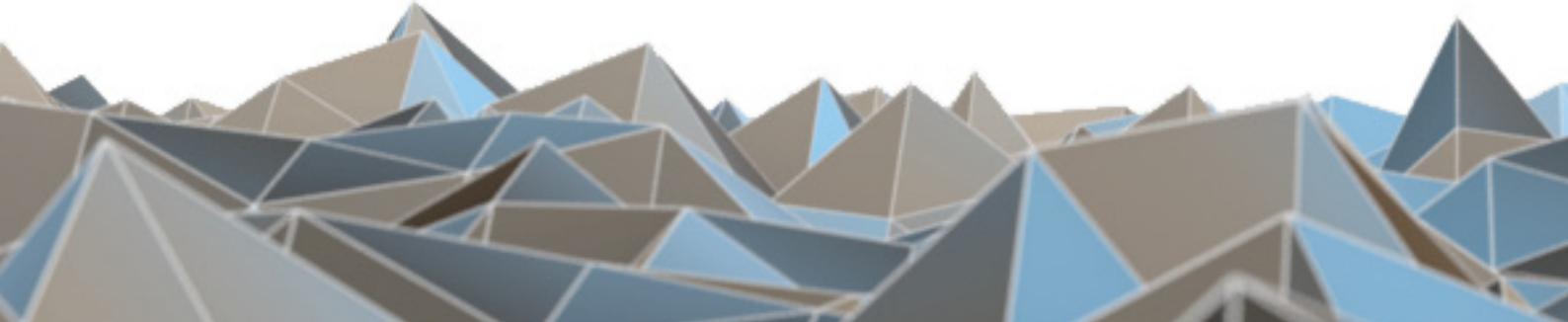
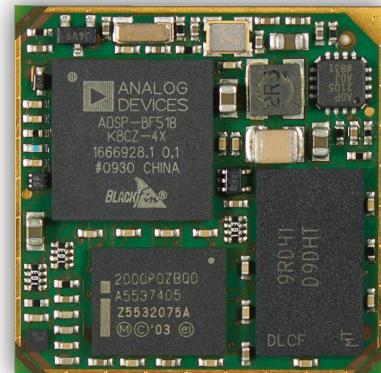


BLUETECHNIX
Embedding Ideas

TCM-BF518

Hardware User Manual

Version 1.5



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Information

For further information on technology, delivery terms and conditions and prices please contact Bluetchnix (<http://www.bluetchnix.com>).

Warning

Due to technical requirements components may contain dangerous substances.

1 Introduction

The Tiny Core Module TCM-BF518 is optimized for performance and size. The module integrates processor, RAM, flash and power supply at a size of 28x28mm! It is based at the high performance ADSP-BF518 from Analog Devices. The Core Module is designed for commercial usage. It addresses 32MByte SDRAM via its 16bit wide SDRAM bus and has an on-board NOR-flash of 8MByte.

1.1 Overview

Figure 1.1 shows the main components of the Core Module TCM-BF518.

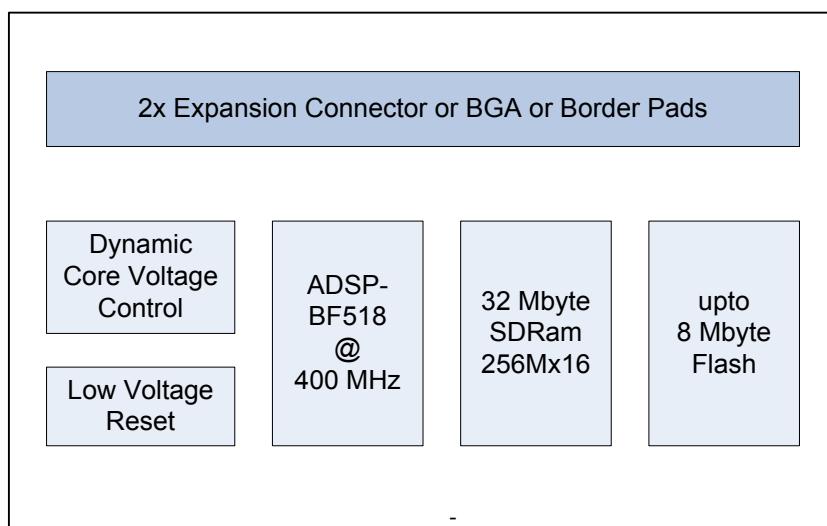


Figure 1.1: Main components of the TCM-BF518 Core Module

1.2 Key Features

- **Blackfin Processor BF518 from Analog Devices**
 - ADSP-BF518KSWZ, 400MHz (0°C to +70°C)
- **32 MB SDRAM**
 - SDRAM Clock up to 133MHz
 - MT48LC16M16A2BG-7 (16Mx16, 256Mbit at 3.3 V)
- **8 MB of Byte Addressable Flash**
 - PF48F2000P0ZBQ0S (32Mx16, 2MByte directly addressable; all 8MByte addressable using external connection of A2x lines via GPIOs)
 - Additional flash memory upon request: It can be connected through the expansion board as parallel flash using asynchronous chip select lines or as SPI flash.
- **Low Voltage Reset Circuit**
 - Resets the module if the supply voltage drops below 2.93V.
- **Core Voltage Control**

- Core voltage 1.35V (0.95V - 1.5V)
- **Peripherals available on all Core Module versions**
 - Power Supply
 - SPORT 0
 - JTAG
 - UART0/UART1
 - TWI (I2C compatible)
 - SPI (Serial Port Interface)
 - PPI (Parallel Port Interface)
 - Boot Mode Pins
 - GPIO's
- **Peripherals only available on the Connector and BGA version**
 - Data Bus
 - Address Bus
 - Further GPIO's
 - Memory Control Signal

1.3 Highlights

- ADSP BF518 DSP,
- 32 MByte SD RAM up to 133Mhz
- 2 MByte Flash
- Very small design (28 x 28 mm)
- Low Power Designs
- Commercial Core Module (0 to +70°C)

1.4 Applications

- VoIP
- Industrial Control
- Motor Control
- Femto Cells
- Networked Audio
- Instrumentation

2 General Description

2.1 Functional Description

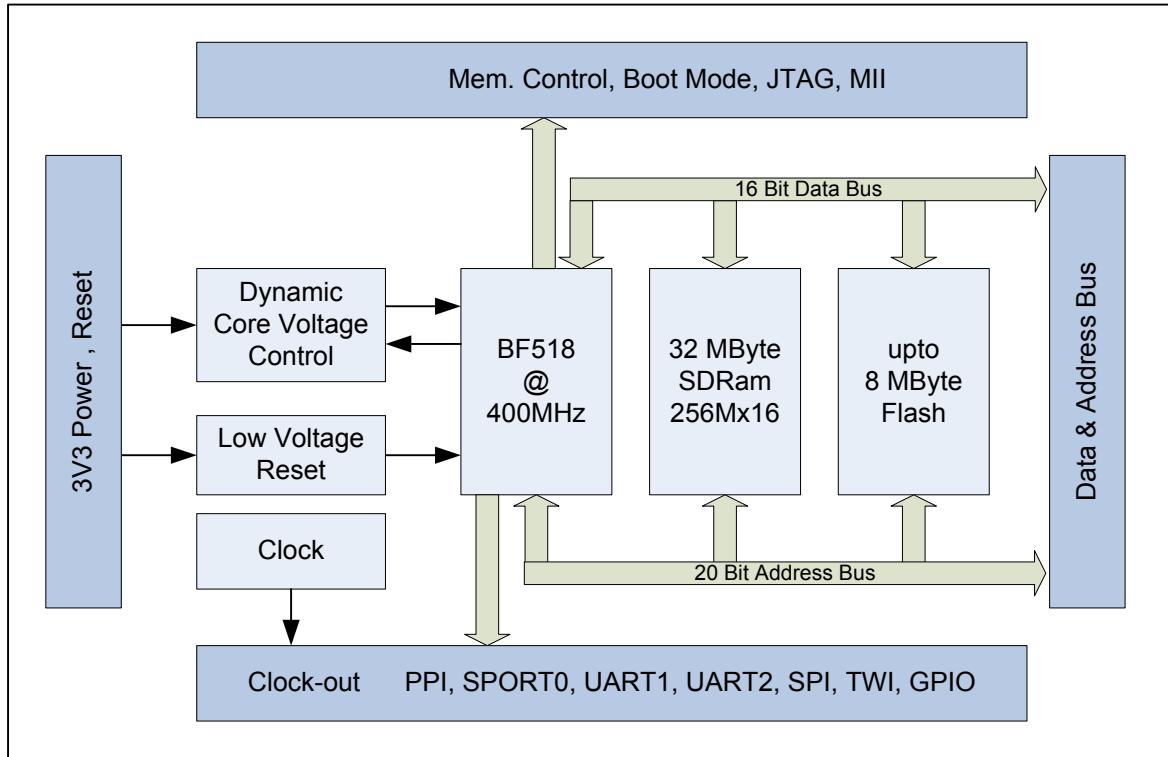


Figure 2.1: Detailed block diagram

Figure 2.1 shows a detailed block diagram of the TCM-BF518 module. Beside the SDRAM and a few other control pins, the TCM-BF518 has most pins of the Blackfin processor on its two 60-pin connectors, or it's BGA, or its Border Pads.

A low voltage reset circuit guarantees a power on reset and resets the system when the input voltage drops below 2.93V for at least 140ms.

2.2 Boot Mode

By default the boot mode = 000 (BMODE2 = Low, BMODE1 = Low, BMODE0=Low). All BMODE pins have on board pull down resistors.

Switch Settings	Boot Mode	Description
BMODE[2..0]		
000	0	Idle - No boot
001	1	Boot from 8- or 16-bit external flash memory
010	2	Boot from internal SPI memory
011	3	Boot from external SPI memory (EEPROM or flash)
100	4	Boot from SPI0 host
101	5	Boot from OTP memory
110	6	Boot from SDRAM
110	7	Boot from UART0

Table 2.1: TCM-BF518 boot modes

Connect BMODE0 to V_{CC} and leave both BMODE1 and BMODE2 pins open to adjust Boot Mode 1. This is the default boot mode for BLACKSheep® OS.

2.3 Memory Map

2.3.1 Core Module Memory

Type	Start address	End address	Size	Comment
Flash*	0x20000000	0x201FFFFF	2MByte	1/4 of 8MB Flash, PF48F2000P0ZBQ0S
SD-RAM	0x00000000	0x01FFFFFF	32MByte	16 bit Bus Micron,MT48LC16M16A2FG

Table 2.2: Memory map

*) Be aware that you have to unlock the flash before starting an erase process!

2.3.2 Externally Addressable Memory (on connector)

The Blackfin processor can address a maximum of 1MB with a single asynchronous memory bank. On this module, each 2MB segment of flash is addressed using 2 asynchronous memory banks. In order to be able to use more than 2MB without using more than 2 banks, GPIOs can be used to select which 2MB section of the FLASH is visible in the memory window of the Blackfin processor. This frees up the remaining banks for the user. Address lines A20 - A24 of the flash are available on the connectors and can be connected to free GPIOs.

Bank	Start address	End address	Size	Comment
0	0x20000000	0x200FFFFFF	1MByte	(Addresses FLASH)
1	0x20100000	0x201FFFFFF	1MByte	(Addresses FLASH)

Table 2.3: Externally addressable memory

NOTE: Pins FA20 to FA24 - These pins are the address lines A20 (FA20) to A24 (FA24) of the Intel P30 Flash and are pulled down by default.



3 Specifications

3.1 Electrical Specifications

3.1.1 Operating Conditions

Symbol	Parameter	Min	Typical	Max	Unit
V_{IN}	Input supply voltage	3.15	3.3	3.45	V
I_{3V3}	3.3V current			625	mA
V_{OH}	High level output voltage		2.4		V
V_{OL}	Low level output voltage			0.4	V
I_{IH}	IO input current			10	μ A
I_{OZ}	Three state leakage current			10	μ A
$I_{DEEPSLEEP}$	V_{IN} current in deep sleep mode		TBD		mA
I_{SLEEP}	V_{IN} current in sleep mode		TBD		mA
I_{IDLE}	V_{IN} current in deep sleep mode		TBD		mA
I_{TYP}	V_{IN} current in with core running at 400 MHz		TBD		mA
$I_{HIBERNATE}$	V_{IN} current in hibernate state		TBD		mA
I_{RTC}	V_{RTC} current		20		μ A
f_{CCLK}	Core clock frequency		400		MHz

Table 3.1: Electrical characteristics

3.1.2 Maximum Ratings

Stressing the device above the rating listed in the absolute maximum ratings table may cause permanent damage to the device. These are stress ratings only. Operation of the device at these or any other conditions greater than those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Symbol	Parameter	Min	Max	Unit
V_{IO}	Input or output voltage	-0.5	3.8	V
V_{IN}	Input supply voltage	3.0	5.5	V
I_{OH} / I_{OL}	Current per pin	0	10	mA
T_{AMB}	Ambient temperature	-40	85	°C
T_{STO}	Storage temperature	-55	150	°C
T_{SLD}	Solder temperature for 10 seconds		260	°C
Φ_{AMB}	Relative ambient humidity		90	%

Table 3.2: Absolute maximum ratings

3.1.3 ESD Sensitivity



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

4 Connector Description

4.1 Connector X1

Pin No.	Signal Name	Type	Function
1	PH2/RSCLK1/SPI1SCK/RSI DATA6	I/O	GPIO/SPORT1 Rx Clock/SPI1 Clock/RSI Data 6
2	PH0/DR1PRI/SPI1SS/RSI_DATA4	I/O	GPIO/SPORT1 Primary Rx Data/SPI1 Device Select/RSI Data 4
3	PH5/TSCLK1/ARDY/PTP_EXT_CLKIN/CDG	I/O	GPIO/SPORT1 Tx Clock/Asynchronous Memory Hardware Ready Control/External Clock for PTP TSYNC/Counter Down Gate
4	PH3/DT1PRI/SPI1MOSI/RSI DATA7	I/O	GPIO/SPORT1 Primary Tx Data/SPI1 Master Out Slave In/RSI Data 7
5	CLKBUF	I/O	Buffered XTAL Output
6	SDA	I/O	TWI Serial Data
7	PG4/RSCLK0/RSI_DATA1/TMR5/TACI5	I/O	GPIO/SPORT0 Rx Clock/RSI Data 1/Timer 5/Timer5 Alternate Capture Input
8	PG1/ERxER/DMAR1/PWM CH	I/O	GPIO/Ethernet MII or RMII Receive Error/DMA Req 1/PWM CH Out
9	Vin 3V3	Power	
10	Vin 3V3	Power	
11	PF0/ETxD2/PPI D0/SPI1SEL2/TACLK6	I/O	GPIO/Ethernet MII Transmit D2/PPI Data 0/SPI1 Slave Select 2/Timer6 Alternate Clock
12	PF2/ETxD3/PPI D2/PWM AL	I/O	GPIO/Ethernet Transmit D3/PPI Data 2/PWM AL Output
13	PF4/ERxCLK/PPI D4/PWM BL/TACLK1	I/O	GPIO/Ethernet MII Receive Clock/PPI Data 4/PWM BL Out/Timer1 Alternate CLK
14	PF6/COL/PPI D6/PWM CL/TACI1	I/O	GPIO/Ethernet MII Collision/PPI Data 6/PWM CL Out/Timer1 Alternate Capture Input
15	PF8/MDC/PPI D8/SPI1SEL4	I/O	GPIO/Ethernet Management Channel Clock/PPI Data 8/SPI1 Slave Select 4
16	PF10/ETxD0/PPI D10/TMR3	I/O	GPIO/Ethernet MII or RMII Transmit D0/PPI Data 10/Timer 3
17	PF12/ETxD1/PPI D12/PWM AL	I/O	GPIO/Ethernet MII Transmit D1/PPI Data 12/PWM AL Output
18	PF14/ETxEN/PPI D14/PWM BL	I/O	GPIO/Ethernet MII Transmit Enable/PPI Data 14/PWM BL Out
19	PG15/SPI0SEL2/PPIFS3/AMS3	I/O	GPIO/SPI0 Slave Select 2/PPI Frame Sync3/Asynchronous Memory Bank Select 3
20	PG6/TFS0/RSI_DATA3/TMR0/PPIFS1	I/O	GPIO/SPORT0 Tx Frame Sync/RSI Data 3/Timer0/PPI Frame Sync1
21	PG8/TSCLK0/RSI_CLK/TMR6/TACI6	I/O	GPIO/SPORT0 Tx Clock/RSI Clock/Timer 6/Timer6 Alternate Capture Input
22	PH7/DR1SEC/UART1RX/TMR7/TACI2	I/O	GPIO/SPORT1 Secondary Rx Data/UART1 Receive/Timer 7/Timer2

Pin No.	Signal Name	Type	Function
			Alternate Clock Input
23	PG10/DR0SEC/UART0RX/TACI4	I/O	GPIO/SPORT0 Secondary Rx Data/UART0 Receive/Timer4 Alternate Capture Input
24	PG14/SPI0MOSI/TMR1/PPIFS2/PWM TRIP	I/O	GPIO/SPI0 Master Out Slave In/Timer1/PPI Frame Sync2/PWM Trip/PTP Auxiliary Snapshot Trigger Input
25	PG12/SPI0SCK/PPICLK/TMRCLK/PT P_PPS	I/O	GPIO/SPI0 Clock/PPI Clock/External Timer Reference/PTP Pulse Per Second Out
26	Bmode0	I - 10k pull down	Boot Mode 0
27	GND	Power	
28	TCK	I - 10k pull up	JTAG Clock
29	TDI	I - 10k pull up	JTAG Data In
30	TRST	I - 4k7 pull down	JTAG Reset
31	EMU	O	JTG Emulation Output
32	TMS	I - 10k pull up	JTAG Mode Select
33	TDO	O	JTAG Data Out
34	Bmode2	I - 10k pull down	Boot Mode 2
35	nc		
36	Bmode1	I - 10k pull down	Boot Mode 1
37	PG13/SPI0MISO4/TMR0/PPIFS1/	I/O	GPIO/SPI0 Master In Slave Out/Timer0/PPI Frame Sync1/PTP Clock Out
38	PG9/DT0SEC/UART0TX/TMR4	I/O	GPIO/SPORT0 Secondary Tx Data/UART0 Transmit/Timer 4
39	PG11/SPI0SS/AMS2/SPI1SEL5/TACL K2	I/O	GPIO/SPI0 Slave Device Select/Asynchronous Memory Bank Select 2/SPI1 Slave Select 5/Timer2 Alternate CLK
40	PH6/DT1SEC/UART1TX/SPI1SEL1/CZ M	I/O	GPIO/SPORT1 Secondary Tx Data/UART1 Transmit/SPI1 Slave Select 1 /Counter Zero Marker
41	PG5/RFS0/RSI_DATA2/PPICLK/TMRC LK	I/O	GPIO/SPORT0 Rx Frame Sync/RSI Data 2/PPI Clock/External Timer Reference
42	PG7/DT0PRI/RSI_CMD/TMR1/PPIFS2	I/O	GPIO/SPORT0 Tx Primary Data/RSI Command/Timer 1/PPI Frame Sync2
43	PF15/RMII PHYINT/PPI D15/PWM_SYNCA	I/O	GPIO/Ethernet MII PHY Interrupt/PPI Data 15/Alternate PWM Sync
44	PF13/ERxD1/PPI D13/PWM BH	I/O	GPIO/Ethernet MII or RMII Receive D1/PPI Data 13/PWM BH Output
45	PF11/ERxD0/PPI D11/PWM AH/TACI3	I/O	GPIO/Ethernet MII Receive D0/PPI Data 11/PWM AH output /Timer3 Alternate Capture Input
46	PF9/MDIO/PPI D9/TMR2	I/O	GPIO/Ethernet Management Channel Serial Data/PPI Data 9/Timer 2
47	PF7/SPI0SEL1/PPI D7/PWMSYNC	I/O	GPIO/SPI0 Slave Select 1/PPI Data 7/PWM Sync
48	PF5/ERxDV/PPI D5/PWM CH/TACI0	I/O	GPIO/Ethernet MII Receive Data Valid/PPI Data 5/PWM CH Out /Timer0 Alternate Capture Input
49	PF3/ERxD3/PPI D3/PWM BH/TACLK0	I/O	GPIO/Ethernet MII Data Receive



Pin No.	Signal Name	Type	Function
			D3/PPI Data 3/PWM BH Output/Timer0 Alternate Clock
50	PF1/ERxD2/PPI D1/PWM AH/TACLK7	I/O	GPIO/Ethernet MII Receive D2/PPI Data 1/PWM AH Output/Timer7 Alternate Clock
51	GND	Power	
52	GND	Power	
53	PG0/MIICRS/RMIICRS/HWAIT 3/SPI1SEL3	I/O	GPIO/Ethernet MII or RMII Carrier Sense or RMII Data Valid/HWAIT/SPI1 Slave Select3
54	PG2/MIITxCLK/RMIIREF_CLK/DMAR0 /PWM CL	I/O	GPIO/Ethernet MII or RMII Reference Clock/DMA Req 0/PWM CL Out
55	PG3/DR0PRI/RSI_DATA0/SPI0SEL5/T ACLK3	I/O	GPIO/SPORT0 Primary Rx Data/RSI Data 0/SPI0 Slave Select 5/Timer3 Alternate CLK
56	SCL	O	TWI Serial Clock
57	PH6/DT1SEC/UART1TX/SPI1SEL1/CZ M	I/O	GPIO/SPORT1 Secondary Tx Data/UART1 Transmit/SPI1 Slave Select 1 /Counter Zero Marker
58	PH4/TFS1/AOE/SPI0SEL3/CUD	I/O	GPIO/SPORT1 Tx Frame Sync/Asynchronous Memory Output Enable/SPI0 Slave Select 3/Counter Up Direction
59	PH7/DR1SEC/UART1RX/TMR7/TACI2	I/O	GPIO/SPORT1 Secondary Rx Data/UART1 Receive/Timer 7/Timer2 Alternate Clock Input
60	PH1/RFS1/SPI1MISO/RSI_DATA5	I/O	GPIO/SPORT1 Rx Frame Sync/SPI1 Master In Slave Out/RSI Data 5

Table 4.1: Connector description X1

4.2 Connector X2

Pin No.	Signal Name	Type	Function
61	A1	O	Address Bus
62	A3	O	Address Bus
63	A5	O	Address Bus
64	A7	O	Address Bus
65	A9	O	Address Bus
66	A11	O	Address Bus
67	A13	O	Address Bus
68	A15	O	Address Bus
69	A17	O	Address Bus
70	A19	O	Address Bus
71	A\B\E\1\	O	Byte Enable
72	FA20	I - 10k pull down	Address Bus
73	FA23	I - 10k pull down	Address Bus
74	VDD OTP	I/O	OTP Power Supply
75	nc	-	-
76	PH5/ARDY	I/O	Hardware Ready Control
77	nc	-	-



Pin No.	Signal Name	Type	Function
78	CLKOUT	O	Clock Output
79	GND	Power	
80	PG15/AMS3	O	Bank Select
81	A\W\E\	O	Write Enable
82	N\MI\	I	Nonmaskable Interrupt
83	D0	I/O	Data Bus
84	D2	I/O	Data Bus
85	D4	I/O	Data Bus
86	D6	I/O	Data Bus
87	D8	I/O	Data Bus
88	D10	I/O	Data Bus
89	D12	I/O	Data Bus
90	D14	I/O	Data Bus
91	D15	I/O	Data Bus
92	D13	I/O	Data Bus
93	D11	I/O	Data Bus
94	D9	I/O	Data Bus
95	D7	I/O	Data Bus
96	D5	I/O	Data Bus
97	D3	I/O	Data Bus
98	D1	I/O	Data Bus
99	R\E\S\E\T\	I/O	Reset
100	PH4/AOE	I/O	Output Enable
101	A\R\E\	O	Read Enable
102	PG11/AMS2	I/O	Bank Select
103	VDD-RTC	Power	
104	nc	-	-
105	nc	-	-
106	nc	-	-
107	nc	-	-
108	FA22	I - 10k pull down	Address Bus
109	FA24	I - 10k pull down	Address Bus
110	FA21 ^{*)}	I - 10k pull down	Address Bus
111	A\B\E\0\	O	Byte Enable
112	A18	O	Address Bus
113	A16	O	Address Bus
114	A14	O	Address Bus
115	A12	O	Address Bus
116	A10	O	Address Bus
117	A8	O	Address Bus
118	A6	O	Address Bus
119	A4	O	Address Bus
120	A2	O	Address Bus

Table 4.2: Connector description X2

^{*)}Be aware that this pin is pulled high on Bluetchnix EVAL-BF5xx! The default BLACKSheep OS Bootloader is flashed on the TCM-BF518 with FA21 pulled high. If the default boot loader should be used then a 220R resistor must be connected between FA21 and 3V3.

5 Application Information

5.1 Supply Voltage Decoupling

5.2 Reset circuit

The reset signal of the flash and the processor are connected to a power monitoring IC. The output can be used as power on reset for external devices, see Figure 5.1.

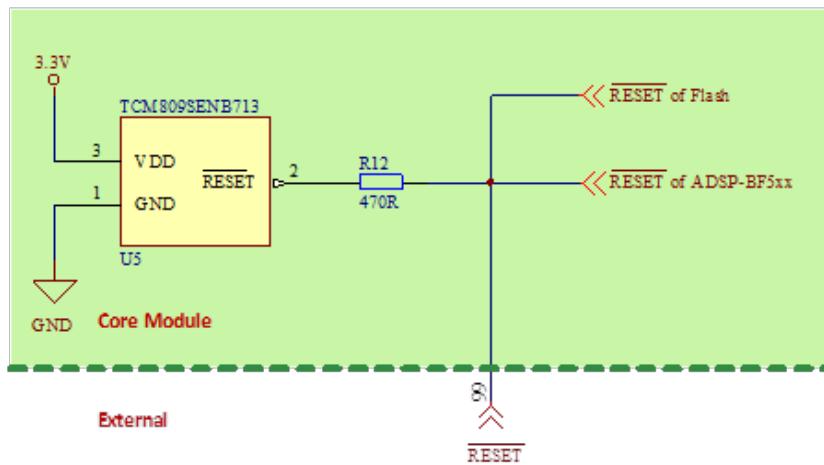


Figure 5.1: Schematic of reset circuit on the Core Module

If reset inputs of other devices are connected to the external RESET pin, an additional driver should be used.

5.3 Application Example Schematics

5.3.1 Connecting a Physical Ethernet Chip

Have a look at our EXT-BF518-ETH schematics, which can be found at <http://www.bluetchnix.com/goto/ext-bf518-eth> to get application examples.

5.3.2 Connecting a USB 2.0 Chip

Have a look at our EXT-BF5xx-USB-ETH2 schematics, which can be found at <http://www.bluetchnix.com/goto/ext-bf5xx-usb-eth2> to get application examples.



6 Mechanical Outline

6.1 Top View

Figure 6.1 shows the top view of the Core Module. All dimensions are given in millimeters!

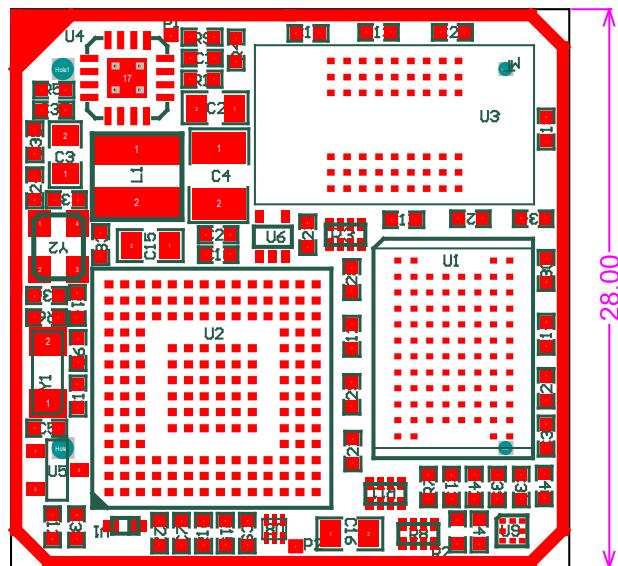


Figure 6.1: Mechanical Outline (top view)

6.2 Bottom View

Figure 6.2 shows the bottom view of the Core Module (connector version).

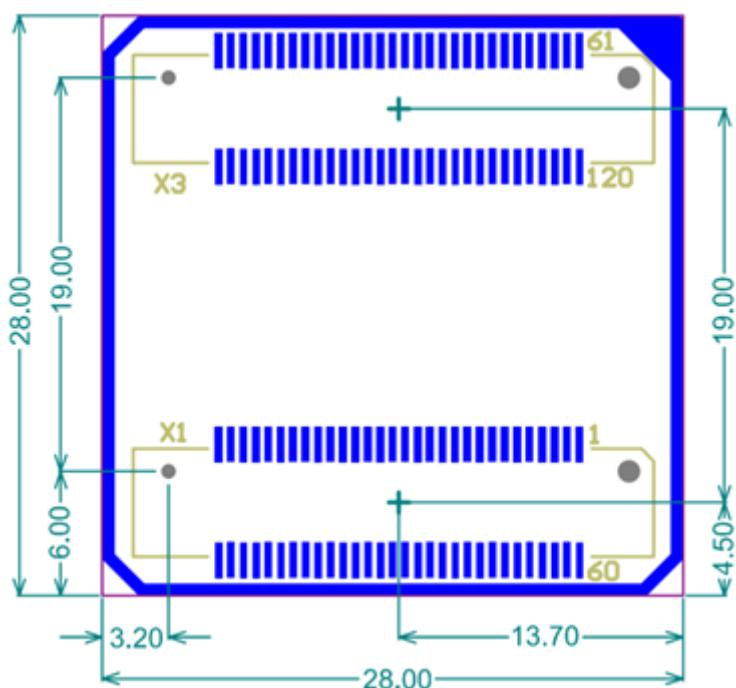


Figure 6.2: Mechanical Outline (bottom view)

6.3 Side View

Figure 6.3 shows a side view of the Core Module with mounted connectors.

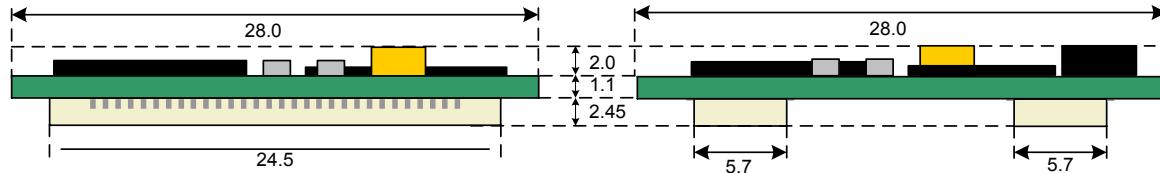


Figure 6.3: Side view with mounted connectors

The total minimum mounting height including receptacle at the baseboard is 5.8mm.

6.4 Footprint

6.5 Connectors

Connector Core Module	Matching Connector	Manufacturer	Manufacturer Part No.
X1	X2	Hirose	FX8-60S-SV
X2	X1	Hirose	FX8-60S-SV

Table 6.1: Core Module connector types

The Core Module features 2 connectors FX8-60P-SV. The base board uses the same connectors but oriented in the opposite way.

7 Support

7.1 General Support

General support for products can be found at Bluetchnix' support site <https://support.bluetchnix.at/wiki>

7.2 Board Support Packages

Board support packages and software downloads are for registered customers only <https://support.bluetchnix.at/software/>

7.3 Blackfin® Software Support

7.3.1 BLACKSheep® OS

BLACKSheep® OS stands for a powerfully and multithreaded real-time operating system (RTOS) originally designed for digital signal processing application development on Analog Devices Blackfin® embedded processors. This high-performance OS is based on the reliable and stable real-time VDK kernel from Analog Devices that comes with VDSP++ IDE. Of course BLACKSheep® OS is fully supported by all Bluetchnix Core-Modules and development hardware.

7.3.2 LabVIEW

You can get LabVIEW embedded support for Bluetchnix Core Modules by Schmid-Engineering AG <http://www.schmid-engineering.ch>.

7.3.3 uClinux

You can get uClinux support (boot loader and uClinux) for Bluetchnix Core Modules at <http://blackfin.uClinux.org>.

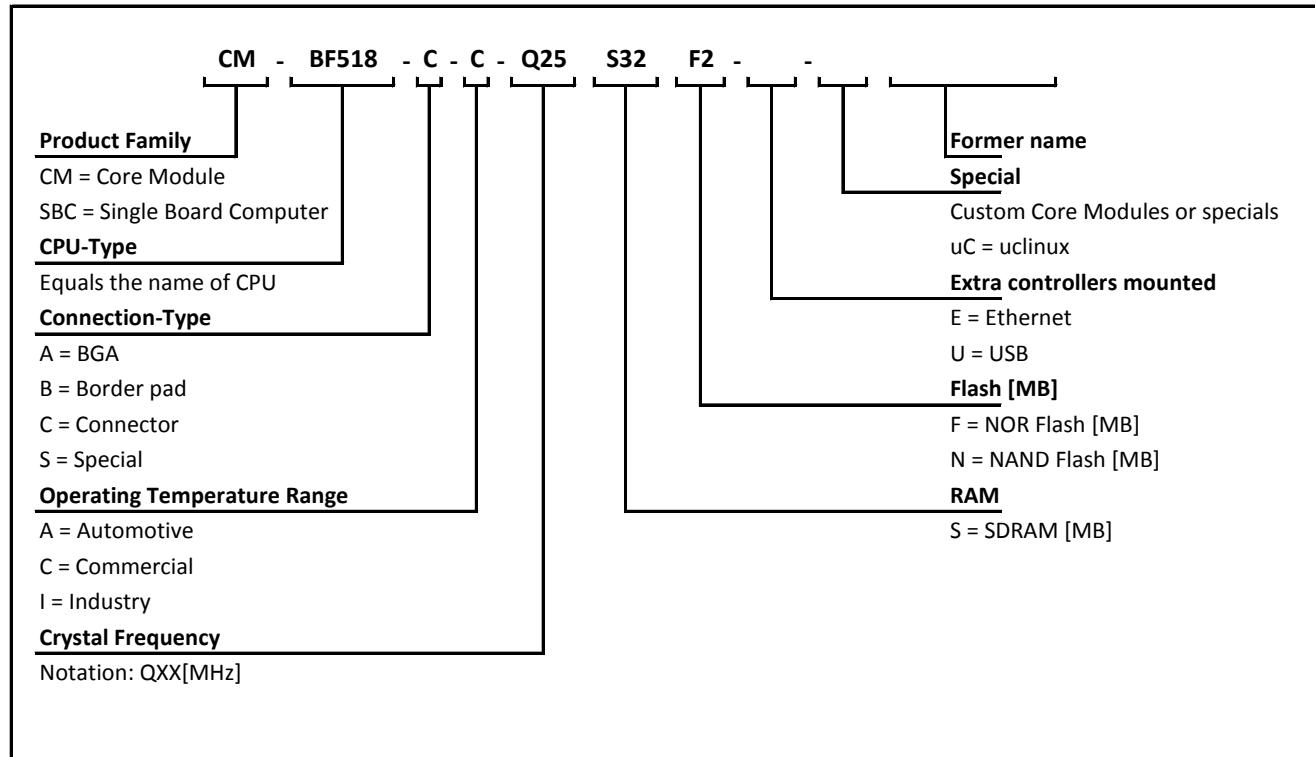
7.4 Blackfin® Design Services

Based on more than seven years of experience with Blackfin, Bluetchnix offers development assistance as well as custom design services and software development.

7.4.1 Upcoming Products and Software Releases

Keep up to date with all product changes, releases and software updates of Bluetchnix at <http://www.bluetchnix.com>.

8 Ordering Information



8.1 Predefined mounting options for TCM-BF518

Article Number	Name	Temperature Range
100-1261-1	TCM-BF518-C-C-Q25S32F2 (TCM-BF518)	Commercial
100-2305-5	EVAL-BF5xx	Blackfin Evaluation Board including accessories
100-2273-1	EXT-BF518-ETH	Ethernet Extender Board for TCM-BF518

Table 8.1: Ordering information

NOTE: Custom Core Modules are available on request! Please contact Bluetchnix (office@bluetchnix.com) if you are interested in custom Core Modules.

9 Dependability

9.1 MTBF

Please keep in mind that a part stress analysis would be the only way to obtain significant failure rate results, because MTBF numbers just represent a statistical approximation of how long a set of devices should last before failure. Nevertheless, we can calculate an MTBF of the Core Module using the bill of material. We take all the components into account. The PCB and solder connections are excluded from this estimation. For test conditions we assume an ambient temperature of 30°C of all Core Module components except the Blackfin® processor (80°C) and the memories (70°C). We use the MTBF Calculator from ALD (<http://www.aldservice.com/>) and use the reliability prediction MIL-217F2 Part Stress standard. Please get in touch with Bluetchnix (office@bluetchnix.com) if you are interested in the MTBF result.

10 Product History

10.1 Version Information

10.1.1 TCM-BF518-C-C-Q25S32F2 (TCM-BF518)

Version	Component	Type
1.0.1	Processor	ADSP-BF518KBCZ-4X 0.1
	RAM	MT48LC16M16A2BG-75 IT:D
	Flash	PF48F2000P0ZBQ0

Table 10.1: Overview PRODUCTNAME product changes

10.2 Anomalies

Version	Date	Description
V1.0	2012 09 19	No anomalies reported yet.

Table 10.2: Product anomalies

11 Document Revision History

Version	Date	Document Revision
5	2012 09 19	Updated to new design. Application examples change: links to our extended boards added Electrical specification update FA21 description added to the pinout
4	2012 02 06	Updated to new design. Removed Boot Mode 3.
3	2010 06 28	Figure 3.5 updated
2	2010 01 26	Layout
1	2009 12 03	First release V1.0 of the Document

Table 11.1: Revision history



12 List of Abbreviations

Abbreviation	Description
ADI	Analog Devices Inc.
AI	Analog Input
AMS	Asynchronous Memory Select
AO	Analog Output
CM	Core Module
DC	Direct Current
DSP	Digital Signal Processor
eCM	Enhanced Core Module
EBI	External Bus Interface
ESD	Electrostatic Discharge
GPIO	General Purpose Input Output
I	Input
I²C	Inter-Integrated Circuit
I/O	Input/Output
ISM	Image Sensor Module
LDO	Low Drop-Out regulator
MTBF	Mean Time Between Failure
NC	Not Connected
NFC	NAND Flash Controller
O	Output
OS	Operating System
PPI	Parallel Peripheral Interface
PWR	Power
RTOS	Real-Time Operating System
SADA	Stand Alone Debug Agent
SD	Secure Digital
SoC	System on Chip
SPI	Serial Peripheral Interface
SPM	Speech Processing Module
SPORT	Serial Port
TFT	Thin-Film Transistor
TISM	Tiny Image Sensor Module
TSC	Touch Screen Controller
UART	Universal Asynchronous Receiver Transmitter
USB	Universal Serial Bus
USBOTG	USB On The Go
ZIF	Zero Insertion Force

Table 12.1: List of abbreviations

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